ABSTRACT

In subroutine 201 and step 205, a best image-forming plane of a projection optical system PL and an offset component of a multipoint AF system are detected as calibration information. During measurement of a wafer alignment mark by an alignment system ALG in step 215, the multipoint AF system detects information related to a surface shape of a surface subject to exposure of a wafer (Z map). In step 219, a Z position order profile regarding position order (Z, θx, θy) related to autofocus leveling control is made, along with an XY position order profile of a wafer stage during scanning exposure, and in step 221, scanning exposure is performed while performing open control based on the position order.